

To: Technology Center 1700
Facsimile Number: 703-872-9310

Total Pages Sent 12

From: Texas Instruments Incorporated
Facsimile: 972-917-4418
Phone: 972-271-1176

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

I Applicant: Steinmann et al

Art Unit: 1785

Serial No.: 09/852,921

Examiner: Deo, D.

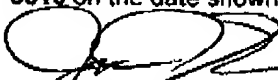
Filing Date: 05/10/01

Docket No.: TI-29881

Title: METHOD OF INTEGRATING A THIN FILM RESISTOR IN A
MULTI-LEVEL METAL TUNGSTEN-PLUG INTERCONNECT

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by
facsimile to the U.S. Patent and Trademark Office at 703-872-
9310 on the date shown below:



Jacqueline J. Garner, Reg. No. 36,144

November 12, 2002
Date

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	<input checked="" type="checkbox"/> AMENDMENT (8 Pages)
<input type="checkbox"/> NEW APPLICATION	<input checked="" type="checkbox"/> EOT 2mths (3 Pages)
<input type="checkbox"/> DECLARATION (# Pages)	<input type="checkbox"/> NOTICE OF APPEAL (# Pages)
<input type="checkbox"/> ASSIGNMENT (# Pages)	<input type="checkbox"/> APPEAL (# Pages)
<input type="checkbox"/> FORMAL DRAWINGS	<input type="checkbox"/> ISSUE FEE (# Pages)
<input type="checkbox"/> INFORMAL DRAWINGS	<input type="checkbox"/> REPLY BRIEF (IN TRIPLICATE) (# Pages)
<input type="checkbox"/> CONTINUATION APP'N (# Pages)	
<input type="checkbox"/> DIVISIONAL APP'N	

NAME OF INVENTOR(S): Steinmann		RECEIPT DATE & SERIAL NO.: Serial No.: 09/852,921	
TITLE OF INVENTION: Method of Integrating a Thin Film Resistor		Filing Date: 05/10/2110	
TI FILE NO.: TI-29881	DEPOSIT ACCT. NO.: 20-0668		
FAXED: 11/12/2002 DUE: 9/13/2002 ATTY/SECY: JGG			

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated
PO Box 855474, M/S 3999
Dallas, TX 75074